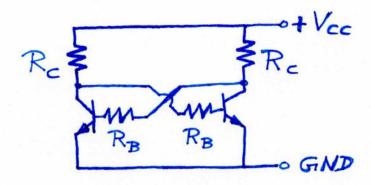
#### ITE - Homework ! - Solution

## Problem 1 SRAM cell

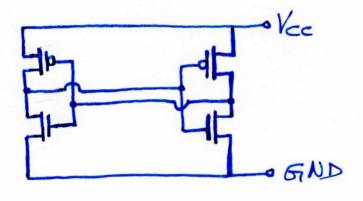
(a) BJT SRAM cell



One of the two branches is ON => Current flowing. One BJT is in saturation (ON or conductive) and a voltage drops across Ra.

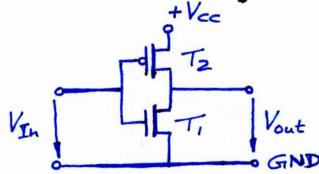
The approximate power consumption is given by  $P = \frac{V_{cc}^2}{Rc}$ 

(b) CMOS FET SRAM cell

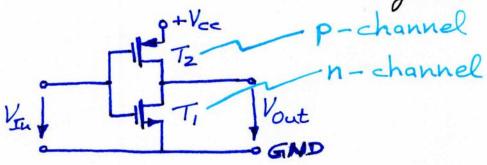


(c) BJT SRAM is not suitable for high degrees of integration because the power consumption is too high => Heat problem.





Alternative circuit diagram



TI turns ON for + Vas

Tz turns ON for - Vas VIn is either + Vcc or GND

 $V_{In} = +V_{ce} \implies T_1 = ON$   $T_2 = OFF$   $\implies V_{out} = O$ 

 $V_{In} = GND \Rightarrow T_i = OFF \quad V_z = ON$   $\Rightarrow V_{out} = + V_{cc}$ 

(b) Small-signal equivalent circuit is of no interest because we have no small-signal signal source.

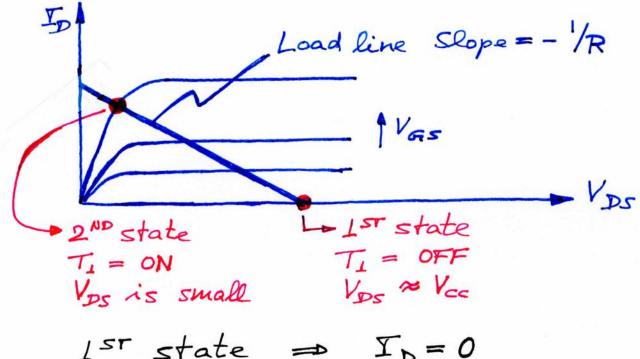
- (c) Static power consumption is always zero, because one of the FETs is always OFF.
- (d) Power consumption of CMOS FET inverter is zero => No heat problem.
- (e) Power consumption of BJT inverter is always >0 (greater Zero).

  BJT has finite input impedance (<∞) ⇒ Big heat problem.

### Problem 3

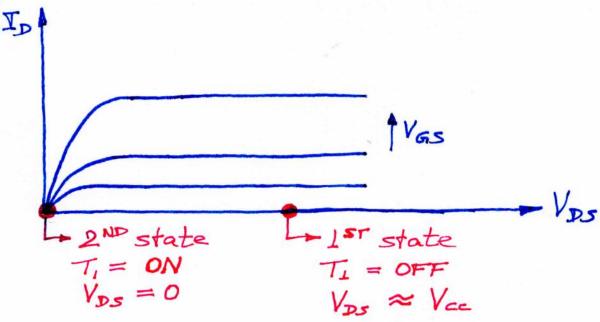
#### CMOS inverter

(a) LHS circuit has resistive load To output characteristic



1<sup>ST</sup> state 
$$\Rightarrow$$
  $I_D = 0$   
2<sup>ND</sup> state  $\Rightarrow$   $I_D \neq 0$ 

(b) RHS circuit has T2 as load



(c) LHS circuit consumes power  $P = V_{cc}^2 / R$ . Power consumption is not good for VLSI (very large scale integration).  $\Rightarrow$  Heat problem.

RHS circuit, a CiMOS circuit, consumes no power - No heat problem - Suitable for VLSI.

# Problem 4

True/false statements

(a) True

Heat problem of BJTS prevents them from being used in VLSI (very large scale integrated circuits).

(b) True

The Zin = 00 characteristic of FETs makes them very suitable for the amplification of weak signals.